

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	0	"10082500"	USPAT	2003/ 04/15 20:30
2	BRS	2	5405809.pn. or 5859471.pn.	USPAT	2003/ 04/15 20:31
3	BRS	16622	(semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT	2003/ 04/16 10:35
4	BRS	1	(semiconductor or chip or die or IC) and encapsulat\$3 and lead and termianl and pad	USPAT	2003/ 04/16 10:33
5	BRS	6352	257/\$.ccls. and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT	2003/ 04/16 10:35
6	BRS	471	(semiconductor or chip or die or IC) and encapsulat\$3 and lead and (pad or contact or terminal) with (protrusion or expos\$3) with encapsulat\$3	USPAT	2003/ 04/16 10:38
7	BRS	1	5405809.pn.	USPAT	2003/ 04/17 13:24
8	BRS	0	("Si" or silicon) near resin with non-transparent	USPAT	2003/ 04/17 13:29
9	BRS	1	6049124.pn.	USPAT	2003/ 04/17 13:29
10	BRS	3	("Si" or silicon) with resin with non-transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 13:30
11	BRS	2	("Si" or silicon) with resin with non-transparent	USPAT	2003/ 04/17 19:24
12	BRS	1	("Si" or silicon) with resin with non-transparent	USPAT	2003/ 04/17 19:23

	Type	Hits	Search Text	DBs	Time Stamp
13	BRS	499	(257/794 or 257/795 or 257/796) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 19:44
14	BRS	251	(257/791 or 257/792 or 257/793) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 19:52
15	BRS	92	(257/736 or 257/748 or 257/749) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 19:57
16	BRS	262	(257/732 or 257/733 or 257/735) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 20:00
17	BRS	279	(257/729 or 257/730 or 257/731) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 20:06
18	BRS	1206	(257/787 or 257/788 or 257/790) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 20:11
19	BRS	1886	(257/666 or 257/668 or 257/676) and (semiconductor or chip or die or IC) and encapsulat\$3 and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/ 04/17 20:39
20	BRS	15	(semiconductor or chip or die or IC) and encapsulat\$3 and lead and (pad or contact or terminal) with (protrusion or expos\$3) with encapsulat\$3	JPO	2003/ 04/17 21:23

	Type	Hits	Search Text	DBs	Time Stamp
21	BRS	24	01128897.pn. or 5866939.pn. or 5405809.pn. or 5859471.pn. or 6445077.pn. or 5264714.pn. or 5894107.pn. or 5677566.pn. or 6303997.pn. or 6114770.pn. or 5951804.pn. or 6130116.pn. or 6232152.pn. or 6468836.pn. or 6297543.pn. or 6326700.pn. or 3627901.pn. or 3678385.pn. or 3930114.pn. or 4506238.pn. or 5157480.pn. or 5207102.pn. or 5436500.pn. or 6455356.pn.	USPAT; JPO	2003/ 04/17 21:30

	Document ID	Issue Date	Current OR	Inventor
1	US 6468836 B1	20021022	438/128	Distefano, Thomas H. et al.
2	US 6455356 B1	20020924	438/123	Glenn, Thomas P. et al.
✓ 3	US 6445077 B1	20020903	257/786	Choi, Ill Heung et al.
4	US 6326700 B1	20011204	257/790	Bai, Jinchuan et al.
5	US 6303997 B1	20011016	257/778	Lee, Seon Goo
6	US 6297543 B1	20011002	257/666	Hong, Sung Hak et al.
7	US 6232152 B1	20010515	438/124	DiStefano, Thomas H. et al.

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8	US 6130116 A	20001010	438/127	Smith, John W. et al.
9	US 6114770 A	20000905	257/784	Akram, Salman et al.
10	US 5951804 A	19990914	156/244.12	Kweon, Young Do et al.
11	US 5894107 A	19990413	174/52.2	Lee, Kyu Jin et al.
✓ 12	US 5866939 A	19990202	257/666	Shin, Won Sun et al.
✓ 13	US 5859471 A	19990112	257/666	Kuraishi, Fumio et al.
14	US 5677566 A	19971014	257/666	King, Jerrold L. et al.
15	US 5436500 A	19950725	257/696	Park, Jong Y. et al.

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✓ 16	US 5405809 A	19950411	438/64	Nakamura, Tetsuro et al.
✓ 17	US 5264714 A	19931123	257/78	Nakaya, Hiroaki et al.
18	US 5207102 A	19930504	73/727	Takahashi, Yoshiharu et al.
19	US 5157480 A	19921020	257/693	McShane, Michael B. et al.
20	US 4506238 A	19850319	333/138	Endoh, Kuniyisa et al.
21	US 3930114 A	19751230	174/52.4	Hodge, Robin H.
22	US 3678385 A	19720718	324/754	Bruner, Peter Martin

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23	US 3627901 A	19711214	257/666	Happ, Marvin B.
24	JP 01128897 A	19890522		HIRATA, ATSUMI